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Part Number: [73644-3212](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location B, Polarizing Key Position G, 144 Circuits

Documents:
[3D Model](#)
[Drawing \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73644](#)
Application Backplane
Comments Standard Press-Fit, Tin/Lead (SnPb)
Component Type PCB Header
Overview [HDM® Backplane Connector System](#)
Product Name HDM®
UPC 800755989496

Physical

Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part Yes
Keying to Mating Part Yes
Material - Metal Phosphor Bronze, Stainless Steel
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 3.50mm
PCB Locator No
PCB Retention Yes
PCB Thickness - Recommended 2.50mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 0.381µm
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C
Termination Interface: Style Through Hole - Compliant Pin



Series

image - Reference only

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Not Reviewed
Low-Halogen Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73644Series](#)

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.
Global

Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	
Backplane Insertion	0622005703
Head for 144 Circuits	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Sales Drawing	SDA-73644-****
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